LA-60 Breadboard for Brick, ARDUINO

1. 6 interconnected round tie points per row in horizontal array provide an ideal placement and more tie point for DIP size chip.
2. Power BUS
   Each of continual interconnected tie point with black line marking COM, and each of continual interconnected tie points with red line marking V1、V2、V3、V4、V5、 V6
3. Interconnected “Round” tie point make your wiring easier, and it accepts solid wires from AWG #22~30 (0.3~0.8mm)
4. Easy combination & expansion
5. Easy insertion & wiring
6. Flexible for simple circuit、Brick、ARDUINO circuits.
7. Dimension : 68 x 60 x 8 (L x W x H, m/m)
8. TIE-POINTS : 360
9. 6 interconnected clip : 60
10. Standard packaging : 1 Breadboard, 8 Brick compatible posts